

1 **ABSTRACT OF THE DISCLOSURE**

2 A method for preparing thin integrated circuits having multiple
3 circuit layers has the following acts of: forming a first circuit layer on a
4 substrate; depositing at least one resin and copper layer on the first circuit
5 layer; forming a second circuit layer on the at least one resin and copper
6 layer; electrically connecting the first and second circuit layers; attaching
7 electronic components to the first or second circuit layers; applying an
8 encapsulant layer to protect the electronic components; and removing the
9 substrate to expose the first circuit layer. By removing the substrate, the
10 integrated circuit is much thinner.